

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiang Dai et al.

Examiner: James M. Mitchell

Serial No.: 10/612,663

Group Art Unit: 2813

Filed: July 2, 2003

Docket No.: 200308566-1

Title: SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE
HAVING A SOLDER COLUMN ARRAY

OK TO ENTER: /J.m.m/ **AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. § 1.312**

02/26/2008

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Amendment after Allowance under 37 C.F.R. § 1.312 is responsive to the Notice of Allowance mailed November 22, 2007. Please amend the above-identified patent application as follows: